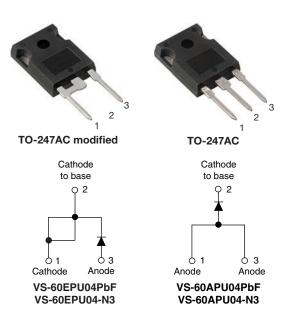
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Vishay Semiconductors

Ultrafast Soft Recovery Diode, 60 A FRED Pt®



PRODUCT SUMMARY								
Dookaga	TO-247AC,							
Package	TO-247AC modified (2 pins)							
I _{F(AV)}	60 A							
V_{R}	400 V							
V _F at I _F	1.25 V							
t _{rr} typ.	See Recovery table							
T _J max.	175 °C							
Diode variation	Single die							

FEATURES

- · Ultrafast recovery time
- · Low forward voltage drop
- 175 °C operating junction temperature
- Designed and qualified according t JEDEC-JESD47
- Material categorization:
 For definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE

BENEFITS

- · Reduced RFI and EMI
- Higher frequency operation
- Reduced snubbing
- · Reduced parts count

DESCRIPTION/APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems.

The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Cathode to anode voltage	V_{R}		400	V					
Continuous forward current	I _{F(AV)}	T _C = 127 °C	60						
Single pulse forward current	I _{FSM}	T _C = 25 °C	600	Α					
Maximum repetitive forward current	I _{FRM}	Square wave, 20 kHz	120						
Operating junction and storage temperatures	T _J , T _{Stg}		- 55 to 175	°C					

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	400	-	-				
Forward voltage	V _F	I _F = 60 A	-	1.05	1.25	V			
		I _F = 60 A, T _J = 175 °C	-	0.87	1.03	i			
		I _F = 60 A, T _J = 125 °C	-	0.93	1.10				
Povorce leekage ourrent	I _R	$V_R = V_R$ rated	-	-	50	μA			
Reverse leakage current		$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-		2	mA			
Junction capacitance	C _T	V _R = 400 V	-	50	-	pF			
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	3.5	-	nΗ			



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DYNAMIC RECOVERY CHARACTERISTICS (T _C = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS				
	t _{rr}	$I_F = 1 A, dI_F/dt = 20$	$I_F = 1 \text{ A, } dI_F/dt = 200 \text{ A/}\mu\text{s, } V_R = 30 \text{ V}$			60				
Reverse recovery time		T _J = 25 °C		-	85	-	ns A nC			
		T _J = 125 °C		-	145	-				
Peak recovery current	I _{RRM}	T _J = 25 °C	$I_F = 60 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_B = 200 \text{ V}$	-	8.8	-				
		T _J = 125 °C		-	15.4	-				
Daviera marana ahama	Q _{rr}	T _J = 25 °C		-	375	-				
Reverse recovery charge		T _J = 125 °C		ı	1120	-				

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Thermal resistance, junction to case	R _{thJC}		-	-	0.70	K/W			
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.2	ı	IVW			
Weight			-	5.5	-	g			
vveignt			-	0.2	-	oz.			
Mounting torque			1.2 (10)	-	2.4 (20)	N ⋅ m (lbf ⋅ in)			
Marking daying		Case style TO-247AC modified	60EPU04						
Marking device		Case style TO-247AC	60APU04						

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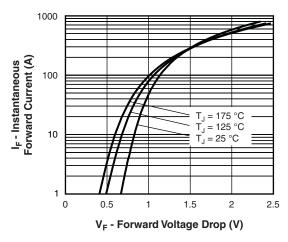


Fig. 1 - Typical Forward Voltage Drop Characteristics

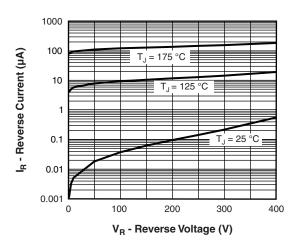


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

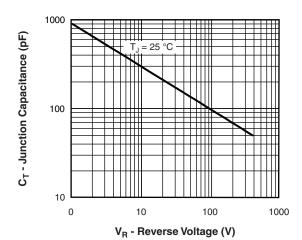


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

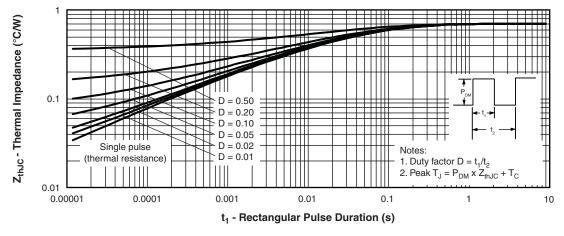


Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics

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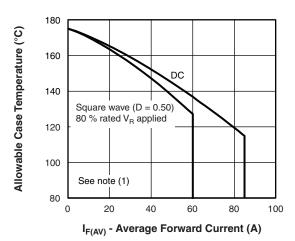


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

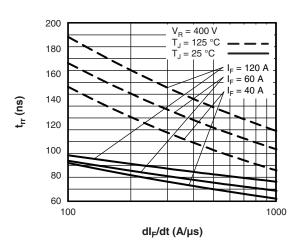


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

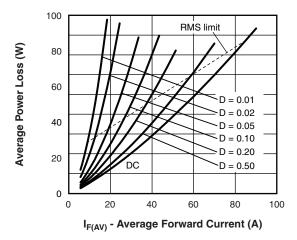


Fig. 6 - Forward Power Loss Characteristics

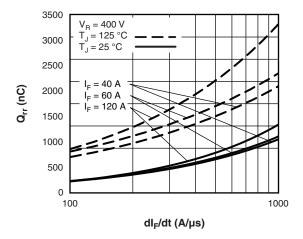


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $^{(1)}$ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = Forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = Inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = 80 % rated V_R

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VS-60EPU04PbF, VS-60EPU04-N3, VS-60APU04PbF, VS-60APU04-N3

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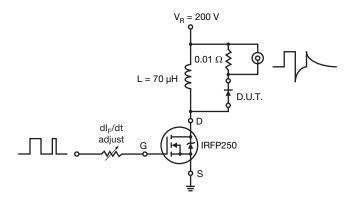
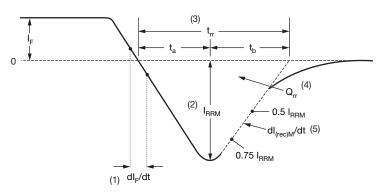


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

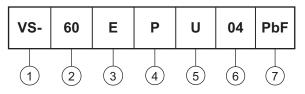
(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (60 = 60 A)

3 - Circuit configuration:

• E = Single diode

• A = Single diode, 3 pins

4 - Package:

P = TO-247AC (modified)

5 - Type of silicon:

U = Ultrafast recovery

6 - Voltage rating (04 = 400 V)

7 - Environmental digit:

PbF = Lead (Pb)-free and RoHS compliant

-N3 = Halogen-free, RoHS compliant and totally lead (Pb)-free

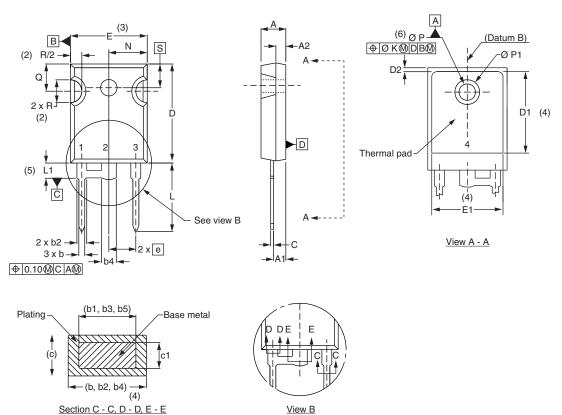
ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-60EPU04PbF	25	500	Antistatic plastic tube						
VS-60EPU04-N3	25	500	Antistatic plastic tube						
VS-60APU04PbF	25	500	Antistatic plastic tube						
VS-60APU04-N3	25	500	Antistatic plastic tube						

LINKS TO RELATED DOCUMENTS								
Dimensions	TO-247AC modified	www.vishay.com/doc?95541						
Differisions	TO-247AC	www.vishay.com/doc?95542						
	TO-247AC modified PbF	www.vishay.com/doc?95255						
Part marking information	TO-247AC modified -N3	www.vishay.com/doc?95442						
Part marking information	TO-247ACPbF	www.vishay.com/doc?95226						
	TO-247AC-N3	www.vishay.com/doc?95007						

Vishay Semiconductors

TO-247 - 50 mils L/F modified

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES		SYMB		
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STIVID		
Α	4.65	5.31	0.183	0.209			D2		
A1	2.21	2.59	0.087	0.102			Е		
A2	1.17	1.37	0.046	0.054			E1		
b	0.99	1.40	0.039	0.055			е		
b1	0.99	1.35	0.039	0.053			ØK		
b2	1.65	2.39	0.065	0.094			L		
b3	1.65	2.34	0.065	0.092			L1		
b4	2.59	3.43	0.102	0.135			N		
b5	2.59	3.38	0.102	0.133			ØΡ		
С	0.38	0.89	0.015	0.035			Ø P1		
c1	0.38	0.84	0.015	0.033			Q		
D	19.71	20.70	0.776	0.815	3		R		
D1	13.08	-	0.515	-	4		S		

SYMBOL	MILLIN	IETERS	INC	INCHES			
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES		
D2	0.51	1.35	0.020	0.053			
Е	15.29	15.87	0.602	0.625	3		
E1	13.46	-	0.53	-			
е	5.46 BSC		0.215	BSC			
ØK	0.254		0.0)10			
L	14.20	16.10	0.559	0.634			
L1	3.71	4.29	0.146	0.169			
Ν	7.62	BSC	0				
ØΡ	3.56	3.66	0.14	0.144			
Ø P1	-	7.39	-	0.291			
Q	5.31	5.69	0.209	0.224			
R	4.52	5.49	0.178	0.216			
S	5.51	BSC	0.217	BSC			

Notes

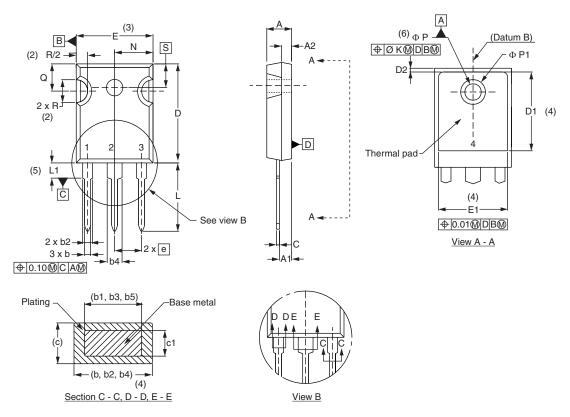
- (1) Dimensioning and tolerance per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension c and Q



Vishay Semiconductors

TO-247 - 50 mils L/F

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES S	SYMBOL	MILLIM	IETERS	INC	HES	NOTES	
STIMBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209			D2	0.51	1.35	0.020	0.053	
A1	2.21	2.59	0.087	0.102			E	15.29	15.87	0.602	0.625	3
A2	1.17	1.37	0.046	0.054			E1	13.46	-	0.53	-	
b	0.99	1.40	0.039	0.055			е	5.46	BSC	0.215	BSC	
b1	0.99	1.35	0.039	0.053			ØK	0.2	254	0.0	10	
b2	1.65	2.39	0.065	0.094			L	14.20	16.10	0.559	0.634	
b3	1.65	2.34	0.065	0.092			L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135			N	7.62	BSC	0	.3	
b5	2.59	3.38	0.102	0.133			ØΡ	3.56	3.66	0.14	0.144	
С	0.38	0.89	0.015	0.035			Ø P1	ı	7.39	-	0.291	
c1	0.38	0.84	0.015	0.033			Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3		R	4.52	5.49	0.178	0.216	
D1	13.08	-	0.515	-	4		S	5.51	BSC	0.217	BSC	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
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Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Revision: 02-Oct-12 Document Number: 91000